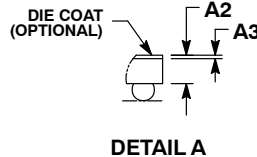
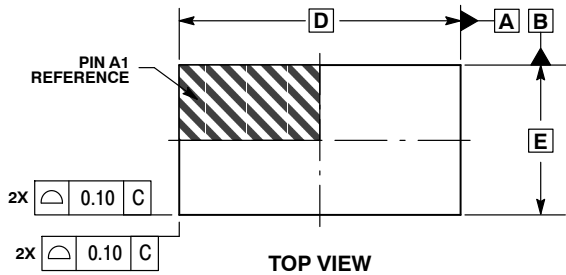


SCALE 4:1

WLCSP28, 3.1x1.65, 0.4P
CASE 567KR
ISSUE O

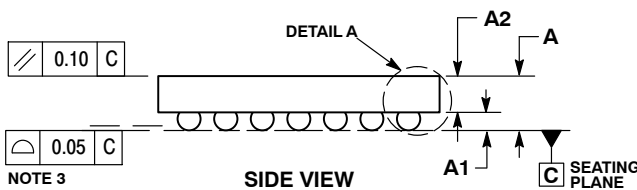
DATE 23 SEP 2014



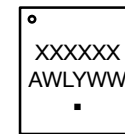
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
A3	0.02	0.04
b	0.24	0.28
D	3.10 BSC	
E	1.65 BSC	
e	0.40 BSC	

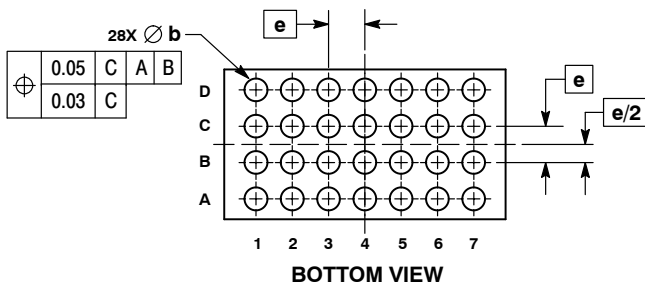


GENERIC MARKING DIAGRAM*

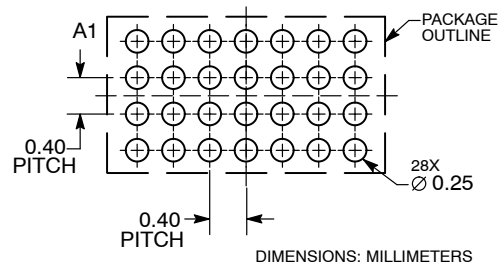


- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP28, 3.1X1.65, 0.4P	PAGE 1 OF 1

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